



Built on PMP20315 RevA PCB.

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TID #:	<a href="#">N/A</a>	Project Title: <a href="#">UCC28722 dual-output Flyback</a>	
Number: <a href="#">PMP20421</a>	Rev: <a href="#">A</a>	Sheet Title:	
SVN Rev: <a href="#">Version control disabled</a>		Assembly Variant: <a href="#">001</a>	Sheet: <a href="#">1</a> of <a href="#">1</a>
Drawn By:	<a href="#">File: PMP20315_BlankSheet.SchDoc</a>		Size: <a href="#">B</a>
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